IN THE CLAIMS:

The text of all pending claims (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claim 3,AMEND claims 1, 2 and 4 and ADD new claim 5 in accordance with the following:

1. (Currently Amended) A semiconductor device having an additional functional element, comprising:

a semiconductor element, on at least ~~on~~ one face of which first, ~~and~~ second, third and fourth electrodes are arranged~~;~~, wherein:

the first electrodes are a plurality of electrodes for signal use, arranged in an outer peripheral region on the one face of the semiconductor element, and

the second, third and fourth electrodes are arranged in a central region on the one face of the semiconductor element and the third and fourth electrodes provide electric power and grounding, respectively;

a wiring board, having first, ~~and~~ second, third and fourth connection pads on a mounting face ~~of~~ on which the semiconductor element is mounted;

a connector ~~connection means for~~ electrically connecting the first electrode with the first connection pad so that a small gap ~~can be~~ is formed between the one face of the semiconductor element and the mounting face of the wiring board when the one face of the semiconductor element is ~~arranged being directed toward~~ facing the mounting face of the wiring board; and

an extremely thin passive element having a specific additional function arranged in the gap formed between ~~a~~ the central region of ~~the second electrode of~~ the semiconductor element and ~~a region of the second connection pad of~~ the wiring board, wherein:

the ~~additional functional~~ extremely thin passive element is connected with the second electrode on the one face ~~thereof~~ of the semiconductor element and also is connected with the second connection pad on the mounting face ~~other face thereof~~ of the wiring board so that a specific electric function can be exhibited~~.~~; and

the third and fourth electrodes are electrically connected with the third and fourth

connection pads on the wiring board, respectively, through a plurality of conductive vias penetrating from one face of the extremely thin passive element to the other face thereof.

2. (Currently Amended) A semiconductor device according to claim 1, wherein:

the connector ~~connection means~~ is a solder bump;

one face of the ~~additional functional~~ extremely thin passive element is connected with the second electrode by ~~means of~~ an ultrasonic connection, anisotropic conductive adhesive film or anisotropic conductive adhesive paste; and

~~the~~ another ~~other~~ face of the ~~additional functional~~ extremely thin passive element is connected with the second connection pad by ~~means of~~ soldering.

3. (Cancelled)

4. (Currently Amended) A semiconductor device according to claim 1, wherein the ~~additional functional element is an~~ extremely thin ~~type~~ passive element ~~or active element, or alternatively the additional functional element~~ is an extremely thin ~~type~~ capacitor, resistor or inductor ~~inductance~~.

5. (New) A semiconductor device having an additional functional element, comprising:

a semiconductor element, on at least one face of which first, second, third and fourth electrodes are arranged, wherein:

the first electrodes are a plurality of electrodes providing a signal, arranged in an outer peripheral region on the one face of the semiconductor element, and

the second, third and fourth electrodes are arranged in a central region on the one face of the semiconductor element and the third and fourth electrodes provide electric power and grounding, respectively;

a wiring board, having first, second, third and fourth connection pads on a mounting face on which the semiconductor element is mounted;

a connector electrically connecting the first electrode with the first connection pad while maintaining a distance between the one face of the semiconductor element and the mounting face of the wiring board when the one face of the semiconductor element is facing the mounting face of the wiring board; and

a passive element, thinner than the distance between the one face of the semiconductor element and the mounting face of the wiring board, having a specific additional function and arranged in the distance between the one face of the semiconductor element and the mounting face of the wiring board, wherein the passive element is connected with the second electrode on the one face of the semiconductor element and connected with the second connection pad on the mounting face of the wiring-board so that a specific electric function can be exhibited; and

the third and fourth electrodes are electrically connected with the third and fourth connection pads on the wiring board, respectively, through a plurality of conductive vias penetrating from one face of the passive element to the other face thereof.